



Layer	Stack up	Supplier	Supplier Description	Description	Type	Processed Thickness	εr	Copper Layer Type	Impedance ID	
1		Taiyo	Soldermask	Soldermask	SolderMask	20.000	4.100			
		CCI	17um Copper Foil	Foil	Foil	36.000		Signal	1	
2		VENTEC	VT47-2116_RC54%	VT47-2116_RC54%	PREPREG	118.800	4.150			
						17.000		Plane		
3		VENTEC	0.305mm	VT-47	Core	305.000	4.200			
						17.000		Signal	2	
4		VENTEC	VT47-2113_RC57%	VT47-2113_RC57%	PREPREG	95.400	4.060			
						18.000		Plane		
5		VENTEC	VT47-2113_RC57%	VT47-2113_RC57%	PREPREG	95.400	4.060			
						18.000		Plane		
6		VENTEC	VT47-2113_RC57%	VT47-2113_RC57%	PREPREG	100.700	4.060			
						17.000		Plane		
7		VENTEC	0.305mm	VT-47	Core	305.000	4.200			
						17.000		Plane		
8		VENTEC	VT47-2116_RC54%	VT47-2116_RC54%	PREPREG	118.800	4.150			
		CCI	17um Copper Foil	Foil	Foil	36.000		Signal	3	
		Taiyo	Soldermask	Soldermask	SolderMask	20.000	4.100			

Copper Thickness = 176.000 | Dielectric Thickness = 1341.800 | Solder Mask Thickness = 40.000 |
Stack Up Thickness = 1517.800 | Stack Up Thickness with Soldermask = 1557.800

Structure Image	Impedance ID	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Target Impedance	Tol (+/- %)	Calculated Impedance	CI Notes-1
	1	Coated Microstrip 1B	1	2	0	191.000	0.000	0.000	50.000	10.000	50.360	
	2	Offset Stripline 1B1A	3	2	4	190.000	0.000	0.000	50.000	10.000	50.430	
	3	Coated Microstrip 1B	8	7	0	191.000	0.000	0.000	50.000	10.000	50.360	

Drill Image	1st Layer	2nd Layer	Drill Type	Minimum Drill Size	Minimum Pad Size	Fill Type
	1	8	Mechanical PTH	0.000	0.000	None